

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

	Stephan Grunow et al.	Docket No.:	TI-35917
Serial No:	10/688,452	Art Unit:	3726
Filed:	10/18/2003	Examiner:	Rick K. Chang
Customer No.:	23494	Conf. No.:	1572
Title:	A Method of Forming a Stacked Interconnect Structure Between Copper Lines of a Semiconductor Circuit		

**AMENDMENT AFTER FINAL UNDER 37 CFR §1.116**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated January 11, 2007. They are respectfully submitted as a full and complete response to that Action.

Please amend the above-referenced application as follows:

There are no **Amendments to the Specification**.

**Amendments to the Claims** are reflected in the listing of claims that begin on page 2 of this paper.

There are no **Amendments to the Drawings**.

The **Remarks** begin on page 5.